

Title (en)

METHOD AND DEVICE FOR THE TEMPERATURE-CRITICAL JOINING OF TWO COMPONENT LAYERS

Title (de)

VERFAHREN UND VORRICHTUNG ZUM TEMPERATURKRITISCHEN FÜGEN ZWEIER BAUTEILSCHICHTEN

Title (fr)

PROCÉDÉ ET DISPOSITIF D'ASSEMBLAGE À TEMPÉRATURE CRITIQUE DE DEUX COUCHES DE COMPOSANT

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Application

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Abstract (en)

[origin: WO2022033869A1] The invention presented relates to a method (100) for the temperature-critical joining of a first electrically conductive component layer (103, 301) having a first constant material thickness and a second component layer (105, 303) having a second constant material thickness, there being disposed on the second component layer (105, 303) at least one electronic component which has a critical temperature below a melting point of the first component layer (103, 301) and of the second component layer (105, 303). The method (100) comprises the following steps: - arranging the first component layer (103, 301) over the second component layer (105, 303) without a gap; - moving a laser beam (101) with constant power along the first component layer (103, 301) with a welding advancement which causes a material forming the first component layer (103, 301) to be partly melted down to the second component layer (105, 303) by means of energy input of the laser beam (101) and which causes only material in a surface region (111, 307) of the second component layer (105, 303) to be melted by means of the energy input.

IPC 8 full level

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